R35-2010BB50R00Fx1QE

◆ Product Features

Case Size	Std. Resistance	Power
2010 mils	50Ω	100 mW

◆ Specifications

Operating Frequency	DC to 48 GHz
Insertion Loss	3.5 dB ± 2dB typical
Operating Temperature Range	55°C to +150°C
Resistive Material	Tantalum Nitride (TaN)
Temperature Coefficient	±150 ppm/°C standard
Resistance Tolerance	±1% (other tolerances available)
Substrate	Alumina (Al_2O_3); other substrates available
Metallization	A = Tantalum/Palladium/Gold (Ta/Pd/Au) R = Titanium/Platinum/Gold (Ti/Pt/Au)

◆ Packaging

Parts are available in Waffle Packs and Tape & Reel.
Contact PPI for additional packaging options.

◆ Mechanical Dimensions

L = 0.020" ± 0.002" (0.508mm ± 0.051mm)
W = 0.010" ± 0.001" (0.254mm ± 0.051mm)
H = 0.010" ± 0.001" (0.254mm ± 0.025mm)

◆ Test Conditions

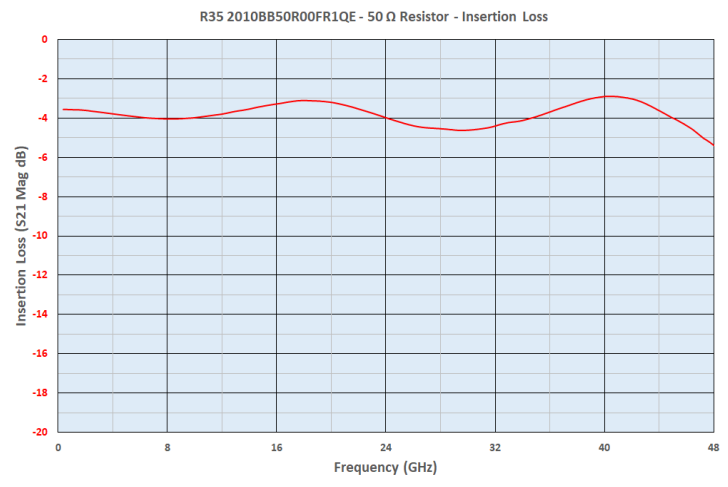
Resistors were measured using 6.6 mil thick RO4350, using typical TRL calibration.

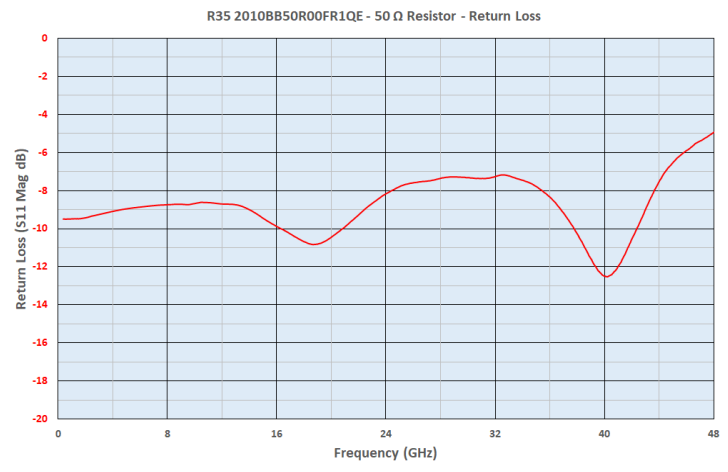
◆ Part Numbering

R 35-2010 BB 50R00 F R1 Q E

- Power Handling: E = 100mW
- TCR: Q = ±150ppm/ºC
- Style: 1
- Metallization: **R** = For Soldering; **A** = For wirebonding
- Tolerance: F = ±1%
- Resistance Value: 50Ω = 50R00; Digits 1-4 are significant; Digit 5 is number of zeros to follow
- Broadband: BB
- Size: .020" x .010"
- Material: 35 = Alumina Resistor

◆ Performance Charts– Insertion and Return Loss Charts





Style: 1 – Recessed Pad

Best for wire bonding or surface mount applications; compatible with Flip Chip configuration.